



For Immediate Release: Tuesday, December 13, 2005

Firan Technology Group Corporation (FTG) Now Offers Rigid-Flex and Flexible Printed Circuit Boards for Aerospace and Defense Customers

December 13, 2005 - FTG announced today it has re-entered the rigid-flex and flex markets to answer the call for a high-end provider of rigid-flex and flexible aerospace compliant printed circuit board products. This capability is being offered through our FTG Circuits – Chatsworth facility.

FTG Circuits - Chatsworth has received DSCC Mil-P-50884, type 4 “adhesiveless” with “etchback”, certification for the manufacture of rigid-flex and flexible printed wiring board products (QPL test reference # 50884-1315-112908). This specification establishes the performance requirements for rigid-flex and flexible printed circuit boards for aerospace and defense users.

The flexible circuit board market has been growing at greater than 20% per year in North America according to industry statistics. The total market is estimated at over \$600M USD in 2005.

“Our goal at FTG is provide the complete range of printed circuit board products to our aerospace customer base from our various manufacturing sites”, noted Mr. Brad Bourne, President and CEO, FTG Corporation. “The addition of a flex and rigid-flex offering is an important step forward for us in achieving this goal”, he added.

FTG Circuits - Chatsworth also provides flexible and rigid-flex product built to IPC 6013 Class 2 and Class 3 commercial standards.

ABOUT FIRAN TECHNOLOGY GROUP CORPORATION

FTG is an aerospace and defence electronics product and subsystem supplier to the North American marketplace. FTG has two operating units.

FTG Circuits is a manufacturer of high technology/high reliability printed circuit boards. Our customers are leaders in the aviation, defence, and high technology industries. FTG Circuits has operations in Toronto, Ontario and Chatsworth, California.

FTG Aerospace manufactures illuminated cockpit panels, keyboards and sub-assemblies for original equipment manufacturers of avionics products as well as airframe manufacturers.

The Company's shares are traded on the Toronto Stock Exchange under the symbol FTG.

This news release contains certain forward-looking statements. Such statements are based on the current expectations of management of the Company and inherently involve numerous risks and uncertainties,

known and unknown, including economic factors and the Company's industry, generally. The preceding list is not exhaustive of all possible factors. Such forward-looking statements are not guarantees of future performance and actual events and results could differ materially from those expressed or implied by forward-looking statements made by the Company. The reader is cautioned to consider these and other factors carefully when making decisions with respect to the Company and not place undue reliance on forward-looking statements. The Company does not undertake and has no specific intention to update any forward-looking statements, written or oral that may be made from time to time by or on its behalf whether as a result of new information, future events or otherwise.

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Additional information can be found at the Company's web site www.firantechnology.com